

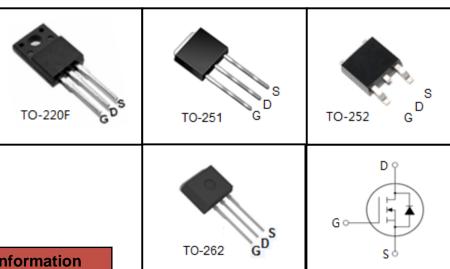
## 700V N-Channel MOSFET

#### **FEATURES**

- Fast switching
- Integrate fast recovery diode
- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability

#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Motor Controls
- Power Factor Correction (PFC)



Device Marking and Package Information					
Device	Package	Marking			
CSFR6N70F	TO-220F	CSFR6N70F			
CSFR6N70K	TO-262	CSFR6N70K			
CSFR6N70U	TO-251	CSFR6N70U			
CSFR6N70D	TO-252	CSFR6N70D			

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted							
Parameter	Symbol		l lmi4				
Parameter	Symbol	TO-220F	TO262	TO-251	TO-252	Unit	
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	700			V		
Continuous Drain Current	I <sub>D</sub>	6			Α		
Pulsed Drain Current (note1)	I <sub>DM</sub>	24				Α	
Gate-Source Voltage	V <sub>GSS</sub>	±30			V		
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	145.8			mJ		
Avalanche Current (note1)	I <sub>AS</sub>	5.4			Α		
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	87.48			mJ		
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	54 83			W		
Operating Junction and Storage Temperature Range	$T_J,T_stg$	-55~+150				°C	

Thermal Resistance						
Borometer	Symbol	Value				l lmit
Parameter		TO-220F	TO-251	TO-252	TO-220	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	2.3		1.5		K/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60		I IVVV	

<b>Specifications</b> $T_J = 25^{\circ}$ C, unless otherwise noted									
Parameter	Symbol	Test Conditions	Value			11:4			
	Symbol	Test Conditions	Min.	Тур.	Max.	Unit			
Static									
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	700			V			
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 700V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μA			
Gate-Source Leakage	I <sub>GSS</sub>	$V_{GS} = \pm 30V$			±100	nA			
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		4.0	V			
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 3.0A$		1.5	1.8	Ω			
Dynamic									
Input Capacitance	C <sub>iss</sub>	V 0V		889		pF			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		86					
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		11.5					
Total Gate Charge	$Q_g$			28		nC			
Gate-Source Charge	$Q_{gs}$	$V_{DD} = 560V, I_{D} = 6.0A, V_{GS} = 10V$		4					
Gate-Drain Charge	$Q_{gd}$			14					
Turn-on Delay Time	t <sub>d(on)</sub>			36		ns			
Turn-on Rise Time	t <sub>r</sub>	$V_{DD} = 350V, I_{D} = 6.0A,$		14					
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 25 \Omega$		143					
Turn-off Fall Time	t <sub>f</sub>			36					
Drain-Source Body Diode Character	istics								
Continuous Body Diode Current	Is				6	A			
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			24				
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25^{\circ}\text{C}, I_{SD} = 3.0\text{A}, V_{GS} = 0\text{V}$			1.4	V			
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 6.0A,$		70		ns			
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /μs		0.13		μC			

#### **Notes**

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%



## **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics (T<sub>J</sub> = 25°C)

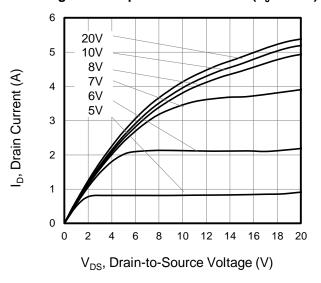


Figure 3. Drain Current vs. Temperature

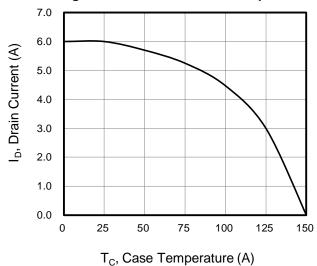


Figure 5. Transfer Characteristics

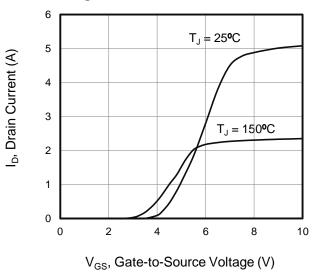


Figure 2. Body Diode Forward Voltage

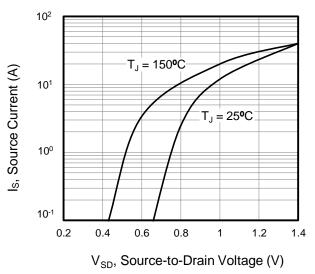
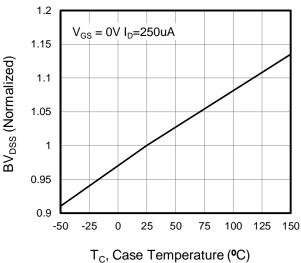
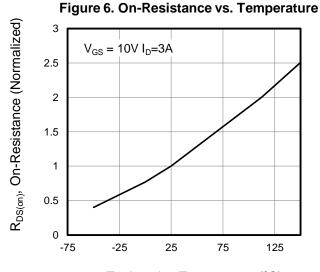


Figure 4.  $BV_{DSS}$  Variation vs. Temperature



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 $T_J$ , Junction Temperature ( ${}^{\circ}C$ )



# **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

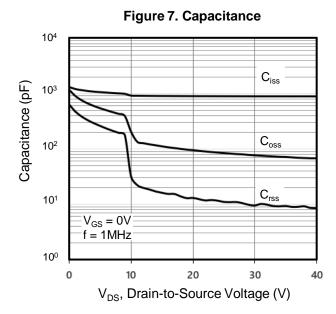


Figure 9. Transient Thermal Impedance TO-262,TO-251,TO-252

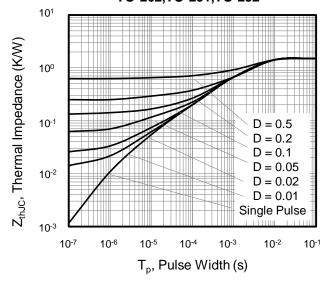


Figure 8. Gate Charge

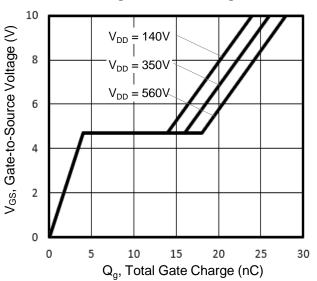


Figure 10. Transient Thermal Impedance

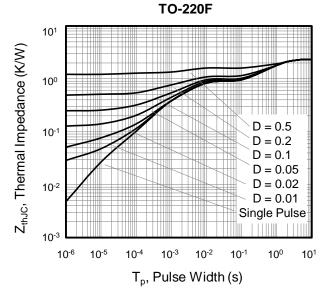




Figure A: Gate Charge Test Circuit and Waveform

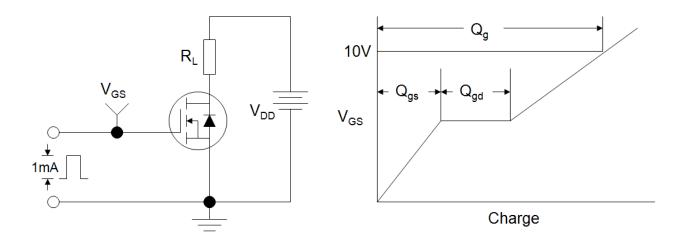


Figure B: Resistive Switching Test Circuit and Waveform

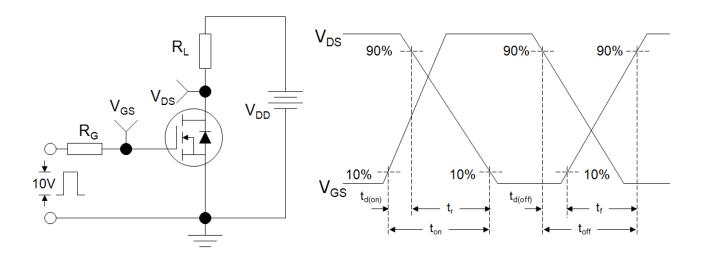
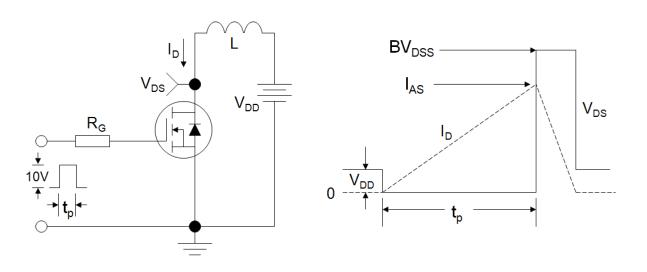
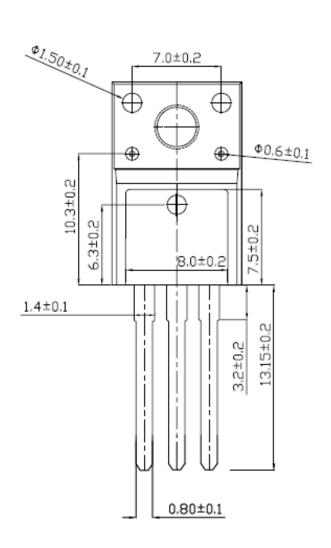


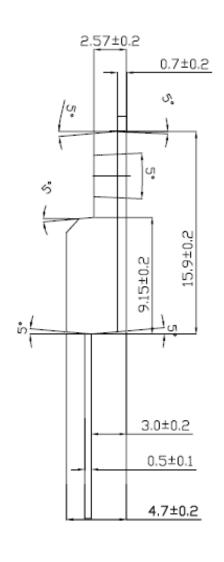
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





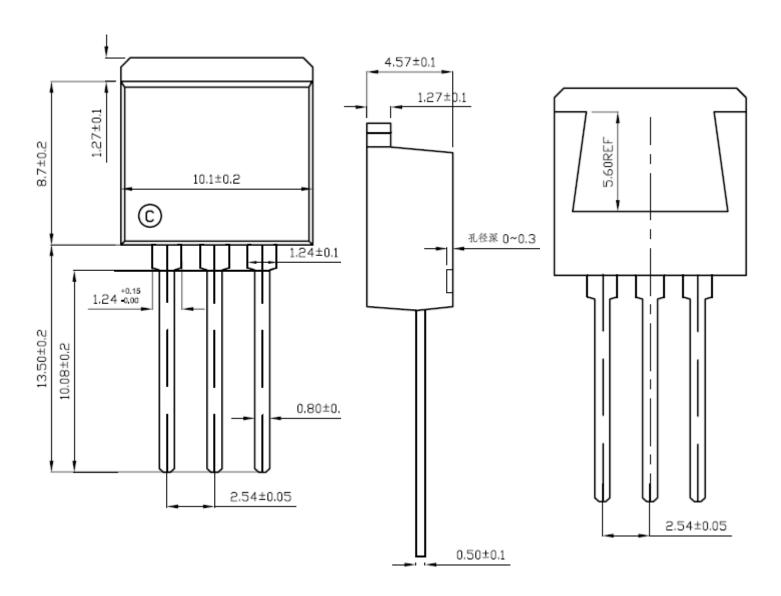
## **TO-220F**





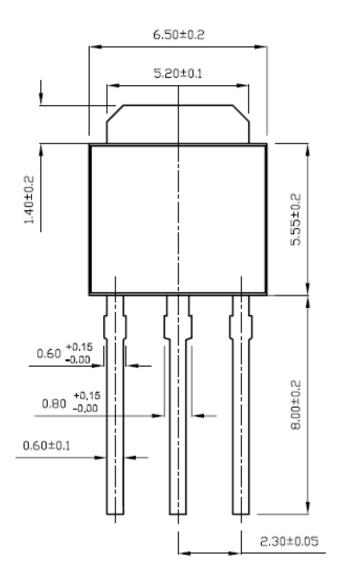


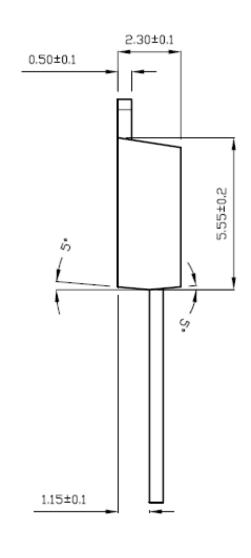
# **TO-262**





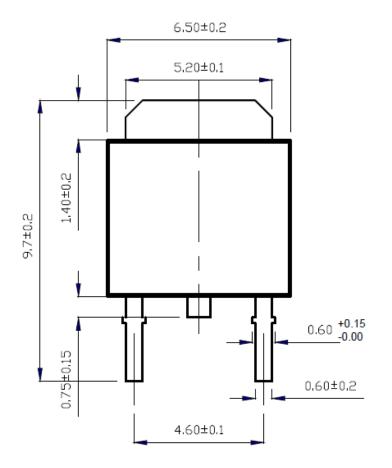
# **TO-251**

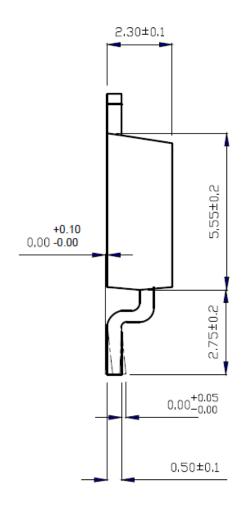






# **TO-252**







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